

# Bill of Materials

PMP4392

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 Project: PMP4392\_PrjPCB  
 Variant: 001

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Footprint	Comment	LibRef	Designator	Description	Quantity
POSCAP BZE	6TPE150MAPB	APXA6R3ARA15	C1, C6, C7, C8	CAP, AL, 150uF, 6.3V, +/-20%, 0.025 ohm, S	4
0603L	GRM1885C2A10	GRM1885C2A10	C2	CAP, CERM, 1000pF, 100V, +/-5%, CoG/NP	1
1206L	GRM31CR72A10	GRM31CR72A10	C3, C4, C5	CAP, CERM, 1uF, 100V, +/-10%, X7R, 1206	3
1210L	GRM32ER61A47	GRM32ER61A47	C9, C12	CAP, CERM, 47uF, 10V, +/-10%, X5R, 1210	2
0805L	GRM21BR71E33	GRM21BR71E33	C10, C11, C21	CAP, CERM, 3.3uF, 25V, +/-10%, X7R, 0805	3
0603L	GRM188R71E47	GRM188R71E47	C13, C18, C19, C20, C25	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	5
0603L	C0603C101J5GA	C0603C101J5GA	C14, C22	CAP, CERM, 100pF, 50V, +/-5%, CoG/NP, 0	2
0603L	GRM188R71E10	GRM188R71E10	C15	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	1
2211	GA352QR7GF10	GRM42A7U3F10	C16	CAP, CERM, 100pF, X1Y2 +/-10%, X7R 221	1
0603L	GRM1885C1H10	GRM1885C1H10	C17	CAP, CERM, 1000pF, 50V, +/-5%, CoG/NP, 0	1
SMB	SMBJ70A-13-F	SMBJ70A-13-F	D1	Diode, TVS, Uni, 70V, 600W, SMB	1
SMA	MURA160T3G	MURA160T3G	D2	Diode, Ultrafast, 600V, 1A, SMA	1
SOT-23L	BAS16-7-F	BAS16-7-F	D3, D7	Diode, Ultrafast, 75V, 0.3A, SOT-23	2
SOT-23L	BZX84C5V1LT1C	BZX84C5V1LT1C	D4	Diode, Zener, 5.1V, 225mW, SOT-23	1
SMA	B360A-13-F	B360A-13-F	D5	Diode, Schottky, 60V, 3A, SMA	1
SOT-23L	D-MMBD6100LT	D-MMBD6100LT	D6	Diode, Switching, Dual, 70 V, 200 mA	1
SOT-23L	BZX84C3V6LT1C	BZX84C3V6LT1C	D8	Diode, Zener, 3.6V, 225mW, SOT-23	1
TRANS_NexF	CSD18534Q5A	CSD18534Q5A	Q1	MOSFET, N-CH, 60V, 50A, SON 5x6mm	1
PG-TDSON-8	BSC320N20NS3	BSC320N20NS3	Q2	MOSFET, N-CH, 200V, 36A, PG-TDSON-8	1
SOT-23L	BC857C-7-F	BC857C-7-F, Di	Q3	Transistor, PNP, 45V, 0.1A, SOT-23	1
MF03A_N	P0102BL	P0102BL	Q4	SCRs, 200V, 0.25A, SOT-23	1
0805L	CRCW080510R0	CRCW080510R0	R1, R4, R11	RES, 10.0 ohm, 1%, 0.125W, 0805	3
1206	RC1206FR-0710	RC1206FR-0710	R2	RES, 10.0 ohm, 1%, 0.25W, 1206	1
0603L	RT0603DRE0710	RT0603DRE0710	R3, R10	RES, 100k ohm, 0.5%, 0.1W, 0603	2
0603	RC0603JR-0756	RC0603JR-0756	R5	RES, 56k ohm, 5%, 0.1W, 0603	1
0603L	RC0603FR-0712	RC0603FR-0712	R6	RES, 120k ohm, 1%, 0.1W, 0603	1
0603	RC0603FR-0727	RC0603FR-0727	R7	RES, 270k ohm, 1%, 0.1W, 0603	1
0805L	RC0805FR-072R	RC0805FR-072R	R8	RES, 2.20 ohm, 1%, 0.125W, 0805	1
0603L	CRCW060310K0	CRCW060310K0	R9	RES, 10.0k ohm, 1%, 0.1W, 0603	1
0603L	RC0603JR-071K	RC0603JR-071K	R12	RES, 1.0k ohm, 5%, 0.1W, 0603	1
0805L	CRCW080551R0	CRCW080551R0	R13	RES, 51 ohm, 5%, 0.125W, 0805	1
0603L	RC0603FR-071K	RC0603FR-071K	R14, R16, R21	RES, 1.20k ohm, 1%, 0.1W, 0603	3
0603L	RC0603FR-0727	RC0603FR-0727	R15	RES, 27.0k ohm, 1%, 0.1W, 0603	1
0603	RT0603DRE0710	RT0603DRE0710	R17	RES, 10.0k ohm, 0.5%, 0.1W, 0603	1
0603L	RC0603FR-071K	RC0603FR-071K	R18	RES, 1.00k ohm, 1%, 0.1W, 0603	1
0603	RG1608P-332-B	RG1608P-332-B	R19	RES, 3.30k ohm, 0.1%, 0.1W, 0603	1
0805_HV	CRCW0805620R	CRCW0805620R	R20	RES, 620 ohm, 5%, 0.125W, 0805	1
0603L	RC0603FR-0718	RC0603FR-0718	R22	RES, 18.0 ohm, 1%, 0.1W, 0603	1
0603L	RC0603FR-0724	RC0603FR-0724	R23	RES, 240k ohm, 1%, 0.1W, 0603	1
0603	RC0603FR-076K	RC0603FR-076K	R24	RES, 6.80k ohm, 1%, 0.1W, 0603	1
0603L	RC0603FR-072K	RC0603FR-072K	R25	RES, 2.20k ohm, 1%, 0.1W, 0603	1
0603L	RC0603FR-0710	RC0603FR-0710	R26, R28	RES, 10.0k ohm, 1%, 0.1W, 0603	2
0603L	RC0603FR-0715	RC0603FR-0715	R27	RES, 150k ohm, 1%, 0.1W, 0603	1
CSV-RM6S-1S	RM6S/ILP	CSV-RM6S-1S-6	T1	750341824, Flyback Transformer, Würth Ele	1
PA1005	PA1005.100NL	PA1005.100NL	T2	Current Sense Transformer, pulseelectronics	1
SO-8	UCC24610D	UCC24610DRB	U1	Secondary-Side SR Controller	1
MUB10A_N	LM5020MMX-1	LM5020MMX-1	U2	100V Current Mode PWM Controller, 10-pin f	1
TLP181	TLP181	PS2811-1-M-A	U3	Low Input Current, Hight CTR Photocoupler	1
SOT-23	TLV431BQDBZT	TLV431ADBZ	U4	IC, Low-Voltage Adjustable Shunt Regulator	1

Approved	Notes

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